## Open Specialty Materials for P3\* powered by OpenAM™















Name	Material Supplier	Category	Description	Sample Applications	More Info
PerFORM HW	Covestro	High Temperature	High stiffness, high temp, ceramic-filled resin (HDT 289°C   Flex modulus 8,700 MPa)	High-temp injection molds	<u>Covestro</u>
RG1100	BASF Forward AM	High Temperature	High temperature, rigid and fast-printing resin (HDT 116°C   Flex modulus 2,880 MPa)	Molds or durable engineering parts	Forward AM
COR Alpha	polySpectra	High Temperature	High temperature resin with good elongation (HDT 115°C   20% E@B)	Bearing and gear components	<u>Polyspectra</u>
RG 3101 L	Evonik	Tough	Well-balanced resin with good stiffness, impact strength, and HDT (Izod 45 J/m   Tg 105°C)	Buckles and rivets	Evonik 3D Printing
Strong-X	Liqcreate	Tough	High stiffness resin (Tg 128°C   Flex modulus 3,500 Mpa)	Heavy duty components	<u>Liqcreate</u>
Formula One	Mechnano	Specialty	Rigid resin with ESD properties (Surface resistivity of 10^7 $\Omega$ )	Electrical housings, PCB carriers	Mechnano
Komitsudo Ceramic	Tethon3D	Specialty	Rigid high temp ceramic-filled resin (Max temp 1,700°C)	Aerospace Thermal Shields	<u>Tethon 3D</u>
CAST011	Arkema	Specialty	High detail, burnout castable resin (Viscosity 115 cP)	Cast structural brackets	Arkema DLP

<sup>\*</sup> Open Material for P3 users can develop or print any DLP materials available to them. For more information on these materials, please contact material suppliers directly.









